Non Silicone Thermal Paste

RoHS Compliant

Applications

- Interface for semiconductors requiring low pressure or spring clamp mounting.
- Consumer electronics
- Set-top boxes
- IP routers
- ECUs Memory and Power modules. CPU to Heat sink
- Transistors
- Diodes
- IGBTs
- Rectifiers
- LED. TEC modules
- Telecommunication hardware and as a gap filler for battery systems.

Features

- 4.5 W/m K thermal conductivity
- Phase transition temperature: 45°C
- Excellent reliability

Characteristic	Test Method	Value
Colour	Visual	Grey
Density (g/cm³)	ASTM D792	2.55
Continuous Use Temperature (°C)	-	-40 to +120
Breakdown Voltage (KV/mm)	ASTM D149	≥3
Thickness of Bonding Layer (μm)	-	≤20
Thermal Conductivity (W/m·K)	ISO 22007-2	4.5
Thermal Impedance (@40psi) (°C·in²/W)	ASTM D5470	0.006
Thermal impedance(@40psi) (°C·cm²/W)	ASTM D5470	0.04
Dielectric Constant (@1MHz)	ASTM D150	7.21
Dielectric Loss (@1MHz)	ASTM D150	2.4 × 10²
Viscosity (Pa·s(23°C)	ASTM E3116 96# 50RPM	400
Shelf Life	-	24 months from shipment date

Part Number Table

Description	Part Number
Thermal Paste , Non Silicone PCM Gel, 4.5W/mK, Syringe, 30g	MPGCSS-045PCM-G-30g

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